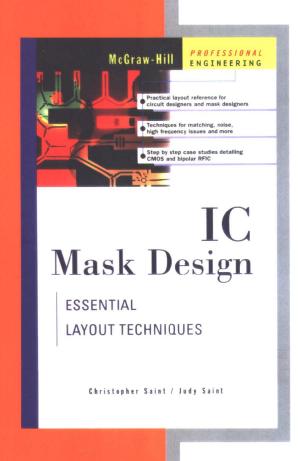


国外大学优秀教材 — 微电子类系列(影印版)

Christopher Saint, Judy Saint

集成电路版图设计





清华大学出版社

TN402 Y15

国外大学优秀教材

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IC Mask Design

Essential Layout Techniques

Christopher Saint Judy Saint



清华大学出版社 ^{北京} Christopher Saint, Judy Saint IC Mask Design—Essential Layout Techniques

EISBN: 007-138996-2

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图书在版编目(CIP)数据

集成电路版图设计 = IC Mask Design / (美) 塞因特 (Saint, C.), (美) 塞因特 (Saint, J.) 著. 一影印本. 一北京: 清华大学出版社, 2003 (国外大学优秀教材——微电子类系列)

ISBN 7-302-07730-4

Ⅰ.集… Ⅱ.①塞… ②塞… Ⅲ.集成电路-计算机辅助制版-高等学校-教材-英文 Ⅳ. TN402

中国版本图书馆 CIP 数据核字(2003) 第 111632 号

出版者:清华大学出版社 地址:北京清华大学学研大厦

http://www.tup.com.cn 邮编: 100084

社总机: (010) 6277 0175 客户服务: (010) 6277 6969

责任编辑: 田志明

印刷者: 北京四季青印刷厂

装 订 者:三河市兴旺装订有限公司

发 行 者: 新华书店总店北京发行所

开 本: 152×228 印张: 30

版 次: 2004 年 1 月第 1 版 2004 年 1 月第 1 次印刷

书 号: ISBN 7-302-07730-4/TN・158

印 数: 1~3000 定 价: 58.00 元

出版前言

微电子技术是信息科学技术的核心技术之一,微电子产业是当代高新技术产业群的核心和维护国家主权、保障国家安全的战略性产业。我国在《信息产业"十五"计划纲要》中明确提出:坚持自主发展,增强创新能力和核心竞争力,掌握以集成电路和软件技术为重点的信息产业的核心技术,提高具有自主知识产权产品的比重。发展集成电路技术的关键之一是培养具有国际竞争力的专业人才。

微电子技术发展迅速,内容更新快,而我国微电子专业图书数量少,且内容和体系不能反映科技发展的水平,不能满足培养人才的需求,为此,我们系统挑选了一批国外经典教材和前沿著作,组织分批出版。图书选择的几个基本原则是:在本领域内广泛采用,有很大影响力;内容反映科技的最新发展,所述内容是本领域的研究热点;编写和体系与国内现有图书差别较大,能对我国微电子教育改革有所启示。本套丛书还侧重于微电子技术的实用性,选取了一批集成电路设计方面的工程技术用书,使读者能方便地应用于实践。本套丛书不仅能作为相关课程的教科书和教学参考书,也可作为工程技术人员的自学读物。

我们真诚地希望,这套丛书能对国内高校师生、工程技术人员以 及科研人员的学习和工作有所帮助,对推动我国集成电路的发展有所 促进。也衷心期望着广大读者对我们一如既往的关怀和支持,鼓励我 们出版更多、更好的图书。

> 清华大学出版社 理工出版事业部 2003.9

IC Mask Design

Essential Layout Techniques

影印版序

集成电路的出现与飞速发展是科技进步的一大奇迹,它不仅给人 类的生产建设和科学研究带来了巨大成功而且也彻底改变了人类文 明和人们日常生活的面目,可以毫不夸张地说,现今每个人生活的方 方面面或多或少都和集成电路密切相关。

集成电路是电子电路,但它又不同于一般意义上的电子电路,它 把成千上万的电子元件包括晶体管、电阻、电容甚至电感集成在微小 的芯片上,正是这种奇妙的设计和制造方式使它为人类社会的进步创 造了空前的奇迹,而使这种奇迹变为现实的正是集成电路版图设计。

集成电路的版图与集成电路的概念是一起诞生的,可以说没有版图就没有集成电路。集成电路版图设计是实现集成电路制造所必不可少的设计环节,它不仅关系到集成电路的功能是否正确,而且也会极大程度地影响集成电路的性能、成本与功耗。近年来迅速发展的计算机、通信、嵌入式或便携式设备中集成电路的高性能低功耗运行都离不开集成电路版图的精心设计,现代集成电路设计中发展起来的全定制与 ASIC 设计、单元库和 IP 库的建立,以及系统芯片(SoC)设计的新概念和方法学也无一不与集成电路版图设计密切相关。

集成电路版图设计是一门技术,它需要设计者具有电路系统原理与工艺制造方面的基础知识。但它更需要设计者的创造性、空间想象力和耐性,需要设计者长期工作的经验和知识的积累,需要设计者对日新月异的集成电路发展密切关注和探索,总之,集成电路版图设计不仅仅是一门技术,也是一门艺术。设计出一套符合设计规则的"正确"版图也许并不困难,但要设计出最大程度体现高性能低功耗低成本、能实际可靠工作的芯片版图却不是一朝一夕能学会的事情。《集成电路版图设计》(IC Mask Design)一书正是从这些角度出发,力图为读者刻画出集成电路版图设计的一幕幕生动活泼的场景,充分展示作者和其他版图设计工程师在多年设计实践中所积累和总结的经验,提供许多在一般电子学教科书和参考书中没有的材料,使读者能在尽可能短的时间内掌握集成电路版图设计的基本规律和技巧,在自己的

工作中得益和发展。

本书可作为本科生和研究生有关集成电路设计方面课程的教科书或指导书,以及从事电路和版图设计的工程技术人员的参考书。全书共分为11章,覆盖了模拟电路、数字电路、标准单元、高频电路、双极型和射频集成电路的版图设计技术,讨论了版图设计中有关匹配、寄生参数、噪声、布局、验证、封装等问题及数据格式,最后还提供了两个实际的例子,CMOS 放大器与双极型混频器的版图设计。这些精心组织的材料不仅提供了版图设计一步一步的细节指导,有利于读者深刻理解版图设计的全过程,而且也展示了在版图设计中的关键技术,使读者可直接应用于日常的工作中。

作者以轻松幽默的文笔为读者提供了一本图文并茂、实用易读的版图设计参考书,它无疑会开阔您的眼界、拓展您的思路、启发您的创新意识,从而更能激起您对于版图设计工作,一项极有价值工作的热爱。

周润德 2003 年 11 月 于清华大学

Introduction

Mask design techniques have developed at an enormous rate. As circuit speeds increase, the mask designer is expected to quickly, efficiently, and accurately translate a schematic into layout, make informed choices based on knowledge of increasingly complex tools, and understand how circuit function can affect layout decisions. Mask design has evolved into a highly valued profession.

Are your skills as sharp as they could be? Are you highly valued?

IC Mask Design: Essential Layout Techniques provides step-by-step detailed guidance on every aspect of the mask design process, including techniques you will use on a daily basis.

This book is written for mask designers and circuit designers alike. A circuit designer who understands layout techniques can help improve circuit function and reduce design times. The mask designer who understands the roles of communication, teamwork, and knowledge of circuit function as they apply to integrated circuit layout can help produce an integrated circuit with superior performance. A good mask designer is crucial to the development of superior integrated circuits.

IC Mask Design covers matching, noise issues, high frequency layout concerns, analog and digital layout, Bipolar RFIC layout techniques, and much more. Two Case Studies included with this book provide insight into the mask design process, demonstrating essential techniques in action. All material is presented in an enjoyable light style, easily readable, with emphasis on practical application.

We hope this book is horizon-expanding for you. We hope you learn to question, to be creative, to think, to innovate, and to become a critical team player

xiv | INTRODUCTION

in designing successful products at your site. Above all, we hope you love your job.

Keep your sense of humor. Enjoy the book.

Christopher Saint Judy Saint

Acknowledgments

We would like to thank the following people for their contributions to the two books IC Layout Basics and IC Mask Design.

Professional support:

Jim Comfort, Hassan Zamat, IBM Management

Noise reduction discussions:

Jerry Twomey

Format assistance:

Tamara Dever, Jack Pryor

McGraw-Hill acquisition and vision:

Steve Chapman

Experience and training:

All the design team members with whom Chris has worked over the years, who helped him learn all these techniques.

Moral support:

Michelle Saint, Jack Pryor, Jack Kennedy, Linda Kennedy, The Pryor Family

Open Letter to Circuit Designers

As a designer, every choice and decision you make within your circuit directly impacts the final piece of silicon that gets built. Circuit design goes beyond the simulator. The physical attributes of your designs can determine whether the circuit thrives or fails. Mask design issues are now, more than ever, part of the circuit design process. Your design is not complete until the circuit is in silicon.

The responsibility of getting your design onto silicon is yours. The responsibility of understanding how your design impacts layout options is yours. The responsibility of communicating circuit requirements to a mask designer is yours. To do all this you must know your mask designers' job as well as they do, if not better.

How can you effectively achieve this difficult part of your job?

First, you need to completely understand your circuit, both electrically and physically. Understanding what your circuit needs to achieve electrically will enable you to make informed decisions about what device sizes to use and what layout techniques to employ. Every time you place a device or an interconnect in your schematic you should be thinking, "What will this look like physically?" You should live, breathe, and think mask design. Every waking thought should be how your circuit will be physically implemented.

Second, you need to understand your manufacturing process intimately—how every component in the process is built and used. If you understand your process, you can make intelligent choices that are based upon documented behaviors instead of wild guesses. Know your manuals. Check your equations. Bother to look them up.

Above all, make sure that your mask designers get all the information they need to do their job effectively. A trap many circuit designers fall into is that they seem to consider a schematic capture tool as merely an electronic front

end to their simulation software. Instead, the schematic database should be considered as the primary source of documentation for a chip design. The following schematic practices can greatly improve any project and reduce rework:

- Annotate current values and paths
- Add layout notes to your schematic
- Place the circuit name onto the schematic
- Keep an effective revision history on the schematic (particularly dates and times)
- Make schematics readable when printed out

This list of practices will not only make your schematics more usable for a mask designer, but also for any subsequent circuit designers who may wish to reuse your innovative, world-shattering concepts.

A small warning: Be careful to choose your mask design techniques wisely. It is easy to overburden your mask designer unnecessarily. For example, if your circuit requires that two resistors match each other to within 5%, then why bother specifying the use of a complex layout technique to produce a match of better than 1%? The increased matching you achieve does not make your circuit any better, but does require extra effort during the mask design phase. Circuit designers who blindly require a mask designer to apply every layout technique in the book (e.g., this one) on their components are potentially costing their company money due to the increased design cycle times.

Know what needs to be communicated to your mask designer. Know how your mask designer can help you. A mask designer is a valuable resource and has probably had extensive exposure to many different circuit design and layout techniques during his or her career. Use that resource. Work as a team. Communicate. Listen. Suggest. Explain. Annotate. Calculate. Learn. Did I say communicate? Especially communicate.

Good layout means successful circuits. If you follow these simple concepts and ideals you will become a cut above the rest. Use this book to build your skills and learn the language of mask design. Today's competetive marketplace demands it.

IC Mask Design Essential Layout Techniques

Contents

Introduction Acknowledgments Open Letter to Circuit Designers		xiii xv xvii	
Chapter 1	Digital Layout	1	
	Chapter Preview	1	
	Opening Thoughts on Digital Layout	1	
	Design Process	2 2 3	
	Verifying the Circuitry Logic	2	
	Compiling a Netlist	3	
	Drive Strength	4	
	Clock Tree Synthesis	5	
	Layout Process	7	
	Floorplanning	7	
	Block Placement	7	
	Gate Grouping	8	
	Block Level Connectivity	8	
	Using Flylines	9	
	Timing Checks	10	
	Placement	11	
	I/O Drivers	12	
	Routing	13	
	Power Nets	13	
	Strapping	14	
	Clock Net Wiring	15	
	Other Critical Nets	16	
	Remaining Nets	16	
	Finishing the Wiring by Hand	17	
	Prefabricated Gate Array Chips	18	
	Verification	19	
	Design Verification	19	
	Physical Verification	20	

	GDSII File	20
	DRC and LVS Checks	20
	Library Management	21
	Summary and Flowchart	22
	Closure on Digital Layout	23
	Here's What We've Learned	24
Chapter 2	Standard Cell Techniques	25
	Chapter Preview	25
	Opening Thoughts on Standard Cell Techniques	25
	Standardized Grids	2ϵ
	Grid-Based Systems	26
	Determining Grid Size	26
	Rule-Based Routers	28
	Directional Layer Technique	29
	Library Rules for Grid-Based Systems	32
	Input and Output Alignment	32
	Fixed Height, Variable Width	34
	Determining Wire Gauge	35
	Common N Well	35
	Half-Grid Cell Sizing	37
	Half Design Rule	38
	Routing Channels	39
	Channel Routers	43
	Antenna Rules	45
	Standardized Input and Output Cells	45
	Using Standardization in Analog Mask Design	46
	Closure on Standard Cell Techniques	47
	Here's What We've Learned	48
Chapter 3	Analog Layout	49
	Chapter Preview	49
	Opening Thoughts on Analog Layout	49
	Digital Skills vs. Analog Skills	50
	Difference of Scale	50
	Difference of Primary Objective	51
	Difference of Teamwork	51
	Difference of Completion Schedule	52
	Difference of Innovation	52
	Difference of Constraints	52
	Difference of Understanding Circuit Techniques	53
	Three Key Ouestions	53

	Contents	ļ	vii
OUTCTION 1 WILL 1 1 1 1 1 1 1 1 1			<i></i>
QUESTION 1: What does this circuit do?	0		55
QUESTION 2: How much current does it tal	ce?		56
Calculating Current Densities			57
QUESTION 2a: Where are the high and low	current		••
paths?			58
Device Orientation		_	59
QUESTION 3: What matching requirements	are there	e?	64
Additional Questions			64
Bipolar Analog			65
Expectations of an Analog Mask Designer			66
Closure on Analog Layout			70
Here's What We've Learned			70
Appendix: Key Questions Discussion			71
Chapter 4 Parasitics			79
Chapter Preview			79
Opening Thoughts on Parasitics			79
Parasitic Capacitance			80
Wire Length			81
Metal Selection			82
Metal over Metal			84
Parasitic Resistance			86
Calculating IR Drops			86
Wiring Options		,	88
Parasitic Inductance			91
Device Parasitics		(92
CMOS Transistor Example		(92
Bipolar Transistor Example		9	93
Full Custom Options		(94
Closure on Parasitics		9	94
Here's What We've Learned		ç	95
Chapter 5 Matching		9	97
Chapter Preview		ç	97
Opening Thoughts on Matching		ç	97
Importance of Layout			8
Importance of Communication		10	
Simple Matching		10	
Root Device Method		10	
Interdigitating Devices		10	
Dummy Devices		10	
Common Centroid		10	

viii | CONTENTS

	Cross-Quading	110
	Symmetry	113
	Matching Signal Paths	114
	Device Size Choices	117
	Closure on Matching	119
	Here's What We've Learned	120
	Rules of Matching	120
Chapter 6	Noise Issues	121
	Chapter Preview	121
	Opening Thoughts on Noise Issues	121
	Noisy Neighbors	122
	Common Sense Noise Solutions	124
	Turn Down the Volume	124
	Rock Band Moves Inside Their House	125
	Go Inside Your Own House	128
	Close All Windows	128
	Call the Sheriff	128
	Move to a New Neighborhood	129
	Wire Solutions	130
	Coaxial Shielding	130
	Differential Signals	132
	Decoupled Power Rails	134
	Stacked Power Rails	135
	Harmonic Interference	136
	Closure on Noise Issues	139
	Here's What We've Learned	139
Chapter 7	Floorplanning	141
	Chapter Preview	141
	Opening Thoughts on Floorplanning	141
	Primary Drivers of Floorplanning	142
	Pin-Driven Planning	143
	Effect of Pin Placement	143
	ESD Supply Strategies	145
	Block-Driven Planning	149
	Signal-Driven Planning	152
	Reshaping Blocks	153
	Sizing Estimates	155
	Leaving Enough Room	155
	Estimating with Existing Circuitry	158
	Closure on Floorplanning	159
	Here's What We've Learned	160

Chapter 8	General Techniques	161
	Chapter Preview	161
	General Techniques	161
	#1 Pick Five or Six Non-minimum Design Rules	162
	#2 Get Thee to the Lowest Parasitic Metal	165
	#3 Plenty of Wide Wiring and Vias	165
	#4 Don't Believe Your Circuit Designer	167
	#5 Use a Consistent Orientation	168
	#6 Don't Go Overboard	169
	#7 Keep Off the Blocks	169
	#8 Care for Your Sensitive and Noisy Signals Early	170
	#9 If It Looks Nice, It Will Work	170
	#10 Learn Your Process	171
	#11 Don't Let Noise Find the Substrate	172
	#12 Spread Your Spinach around Your Dinner Plate	172
	#13 Copy and Rename Cells before Making Changes	175
	#14 Remember Your Hierarchy Level	176
	#15 Build-in Easy Metal Revisions	177
	#16 Draw Big Power Buses	182
	#17 Break Up Large Circuits	184
	Closure on General Techniques	184
	Ancient Secrets of Mask Design	185
Chapter 9	Packaging	187
Chapter 9		
Chapter 9	Chapter Preview	187
Chapter 9	Chapter Preview Opening Thoughts on Packaging	187 187
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods	187 187 188
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding	187 187 188 189
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding	187 187 188 189 190
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology	187 187 188 189 190 191
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging	187 187 188 189 190 191 192
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging	187 187 188 189 190 191 192 193
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance	187 187 188 189 190 191 192 193 193
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule	187 187 188 189 190 191 192 193 193
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap	187 187 188 189 190 191 192 193 193 194 195
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length	187 187 188 189 190 191 192 193 193 194 195
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length Pad Distribution	187 187 188 189 190 191 192 193 193 194 195 195
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length Pad Distribution Sizing Estimates	187 187 188 189 190 191 192 193 193 194 195 195 196 197
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length Pad Distribution Sizing Estimates Pad-Limited Design	187 187 188 189 190 191 192 193 193 194 195 195 196 197
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length Pad Distribution Sizing Estimates Pad-Limited Design Core-Limited Design	187 187 188 189 190 191 192 193 193 194 195 195 196 197 197
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length Pad Distribution Sizing Estimates Pad-Limited Design Core-Limited Design Package Maximum Check	187 187 188 189 190 191 192 193 193 194 195 195 196 197 197 199 200
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length Pad Distribution Sizing Estimates Pad-Limited Design Core-Limited Design Package Maximum Check Final Die Size Calculations	187 187 188 189 190 191 192 193 193 194 195 195 196 197 197 199 200
Chapter 9	Chapter Preview Opening Thoughts on Packaging Bonding Methods Ultrasonic Wedge Bonding Ultrasonic Ball Bonding Flip Chip Technology Multi-Tier Packaging Issues in Packaging Overall Appearance 45-Degree Rule Minimal Silicon Overlap Wire Length Pad Distribution Sizing Estimates Pad-Limited Design Core-Limited Design Package Maximum Check Final Die Size Calculations Filling Pad Gaps	187 187 188 189 190 191 192 193 193 194 195 195 196 197 197 199 200